IPC ASSOCIATION CONNE ELECTRONICS INDUS	Material Compo © Copyright 2005. IPo	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.				This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lower level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.									
752-21.1		IPC Web Site for Information on IPC-1752 Standard Form Type http://www.ipc.org/IPC-175x Distribute				Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Mater					rials and N	ials and Mfc Information			
Supplier Info												-			
Company name*			Company uni	Company unique ID			Unique ID Authority					Response Date*			
nsemi											2024-0	2024-04-12			
Contact Name		Title - Contact			I	Phone - Contact*				Email	Email - Contact*				
Product-Env-St	ewards	Product Enviro Compliance				NA				Produ	Product-Env-Stewards@onsemi.com				
uthorized Repr	resentative*	Title - Representative			I	Phone - Representative*				Email	Email - Representative*				
Product-Env-Stewards Product				Product Enviro Compliance			NA				Produ	Product-Env-Stewards@onsemi.com			
Requ	ester Item Number	Mfr Item Number		Mfr Item Name			Effective Date	e Versi	ion	Manufacturing Site		Weight*	UOM	Unit Type	
		AMIS49	AMIS49587C5872RG PLC MODE		MODEM 2400BAUD		2024-04-12 PHG		PHG	187.24		mg	Each		
Ianufacturii	ng Proccess Informati	ion				·		-					,		
Terminal Plating / Grid Array Material To			Terminal Base Alloy J-STD-020 MS		SL Rating	Peak Process Body Temperatur		re Max Time at Pea	k Tempera	ature Numb	per of Reflow Cyc	eles			
Matte Tin (Sn) - annealed		CU Alloy 3			260	260 C		30	seco	nds 3					
omments															
ITENTION: N	MSL 3 Rated item requires	Bake and D	ry Pack (after	electrical test)											
or more inform	ation regarding material c	omposition	please refer to	page 3											

RoHS Material Composition Declaration			Declaration Type *	Detail	ed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).											
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier have provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier have provided as part of that agreement, will be the sole and exclusivesource of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form. In the absence of such written agreement, the warranty rights and/or remedies of Supplier's Standard Terms and Conditions of Sale applicable to such part shall apply.											
RoHS Declaration * 1 - Item	(s) does not contain RoHS restricted substar	nces per the definition above	Supplier A	cceptance *	Accepted						
Exemption: If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions.											
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
		e "Accepted" on the Supplier Acceptance	drop-down. This will display the signature a	rea. Digitally sign t	the declaration (if required by the						

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	17.44	mg	Supplier	Silicon (Si)	7440-21-3		17.44	mg
Die Attach	5.48	mg		Epoxy resin	proprietary data		0.137	mg
			Supplier	Silver (Ag)	7440-22-4		4.384	mg
			Supplier	Polybutadiene polymer	Proprietary Data		0.3562	mg
			Supplier	Acrylic resins	Proprietary Data		0.6028	mg
Lead Frame	98.48	mg	Supplier	Silver (Ag)	7440-22-4		0.1379	mg
			Supplier	Zinc (Zn)	7440-66-6		0.0985	mg
			Supplier	Iron (Fe)	7439-89-6		2.0681	mg
			Supplier	Copper (Cu)	7440-50-8		96.0771	mg
			Supplier	Phosphorus (P)	7723-14-0		0.0985	mg
Mold Compound-Black	63.52	mg		Epoxy resin	proprietary data		3.176	mg
			Supplier	Carbon Black (C)	1333-86-4		0.3176	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		56.8504	mg
			Supplier	Phenolic Resin (Novolac)	9003-35-4		3.176	mg
Plating	0.6	mg	Supplier	Tin (Sn)	7440-31-5		0.6	mg
Wire Bond - Au	1.72	mg	Supplier	Gold (Au)	7440-57-5		1.72	mg